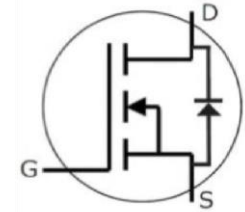
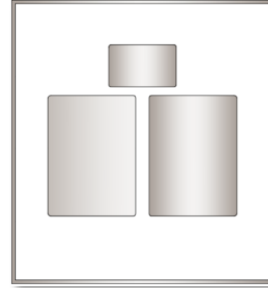


CPM2-1200-0080A

Wolfspeed SiC Gen 2nd MOSFET

Description

This is the Wolfspeed's 2nd generation of high performance silicon carbide MOSFET in a packageless bare die format to be implemented into any custom module design. The high blocking voltage with low on-resistance, high speed switching with low capacitance make this MOSFET ideal for high frequency switching application including solar inverters and motor drives.



Package Types: Bare Die
PN's: CPM2-1200-0080A

Features

- Enhanced 2nd Generation SiC MOSFET
- High blocking voltage with low on-resistance
- High speed switching with low capacitance
- Fast intrinsic diode with low reverse recovery

Applications

- Server & Telecom PSU
- Motor Drives
- Solar Inverters
- SMPS
- DC/DC Converters

Absolute Maximum Ratings

Stress beyond those listed under absolute maximum ratings may damage the device.

Parameter	Symbol	Rating	Unit
Drain-Source Voltage, across T_{vj}	$V_{DS(max)}$	1200	V
Maximum Gate-Source Voltage, Peak Transient Capability	$V_{GS(max)}$	-10/+25	V
Continuous Drain Current, $V_{GS} = 15V$, assumes die packaged in TO-247 package with $R_{th(j-c)} < 0.65$ K/W	I_D	$T_c = 25^\circ C$	36
		$T_c = 100^\circ C$	24
Pulsed Drain Current, t_p limited by $T_{vj(max)}$	$I_{D(pulse)}$	80	A
Virtual Junction and Storage Temperature	T_{VJ}, T_{stg}	-55 to +150	$^\circ C$
Maximum Processing Temperature, in non-reactive ambient	T_{proc}	325	$^\circ C$

Recommended Operating Conditions

Parameter	Symbol	Rating	Unit
Recommended Operating Gate - Source Voltage	$V_{GS(op)}$	-5/+20	V

Electrical Characteristics ($T_{VJ} = 25^{\circ}\text{C}$)

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	1200			V	$V_{GS} = 0\text{ V}$, $I_D = 100\text{ }\mu\text{A}$
Gate Threshold Voltage	$V_{GS(th)}$	2	2.9	4	V	$V_{DS} = V_{GS}$, $I_{DS} = 5\text{ mA}$
			2.4		V	$V_{DS} = V_{GS}$, $I_{DS} = 5\text{ mA}$, $T_{VJ} = 150^{\circ}\text{C}$
Zero Gate Voltage Drain Current	I_{DSS}		1	100	μA	$V_{DS} = 1200\text{ V}$, $V_{GS} = 0\text{ V}$
Gate-Source Leakage Current	I_{GSS}			250	nA	$V_{GS} = 20\text{ V}$, $V_{DS} = 0\text{ V}$
Drain-Source On-State Resistance	$R_{DS(on)}$		80	98	m Ω	$V_{GS} = 20\text{ V}$, $I_D = 20\text{ A}$
			144			$V_{GS} = 20\text{ V}$, $I_D = 20\text{ A}$, $T_{VJ} = 150^{\circ}\text{C}$
Transconductance	g_{fs}		10		S	$V_{DS} = 20\text{ V}$, $I_{DS} = 20\text{ A}$
			9			$V_{DS} = 20\text{ V}$, $I_{DS} = 20\text{ A}$, $T_{VJ} = 150^{\circ}\text{C}$
Input Capacitance	C_{iss}		1130		pF	$V_{GS} = 0\text{ V}$, $V_{DS} = 1000\text{ V}$ $f = 1\text{ MHz}$ $V_{AC} = 25\text{ mV}$
Output Capacitance	C_{oss}		92			
Reverse Transfer Capacitance	C_{rss}		7.5			
C_{oss} Stored Energy	E_{oss}		50		μJ	$V_{DS} = 1000\text{ V}$, $f = 1\text{ MHz}$
Internal Gate Resistance	$R_{G(int)}$		3.9		Ω	$f = 1\text{ MHz}$, $V_{AC} = 25\text{ mV}$
Gate to Source Charge	Q_{gs}		17		nC	$V_{DS} = 800\text{ V}$, $V_{GS} = -5\text{ V}/20\text{ V}$ $I_{DS} = 20\text{ A}$ Per IEC60747-8-4 pg 21
Gate to Drain Charge	Q_{gd}		29			
Total Gate Charge	Q_g		71			

Reverse Diode Characteristics ($T_{VJ} = 25^{\circ}\text{C}$)

Characteristics	Symbol	Typ.	Max.	Unit	Test Conditions
Diode Forward Voltage	V_{SD}	4.3		V	$V_{GS} = -5\text{ V}$, $I_{SD} = 10\text{ A}$
		3.8		V	$V_{GS} = -5\text{ V}$, $I_{SD} = 10\text{ A}$, $T_{VJ} = 150^{\circ}\text{C}$
Reverse Recovery Time	t_{rr}	24		ns	$V_{GS} = -5\text{ V}$, $I_{SD} = 20\text{ A}$, $V_R = 800\text{ V}$ $\text{dif}/\text{dt} = 2400\text{ A}/\mu\text{s}$
Reverse Recovery Charge	Q_{rr}	152		nC	
Peak Reverse Recovery Current	I_{rrm}	10		A	

Typical Performance

All the graphs are based on a die placed in a TO-247-4L package.

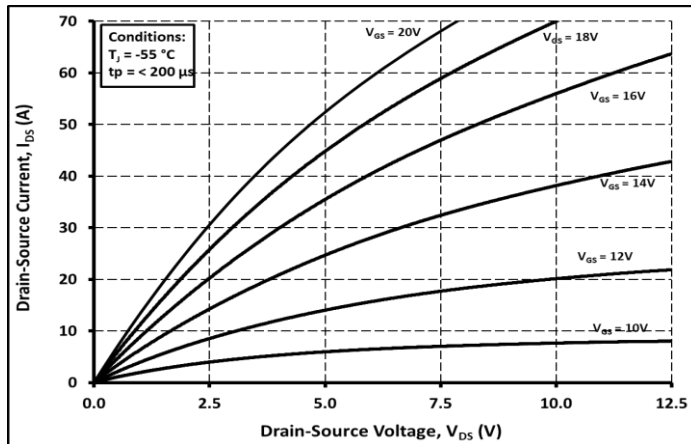


Figure 1.

Output Characteristics $T_{vj} = -55\text{ }^{\circ}\text{C}$

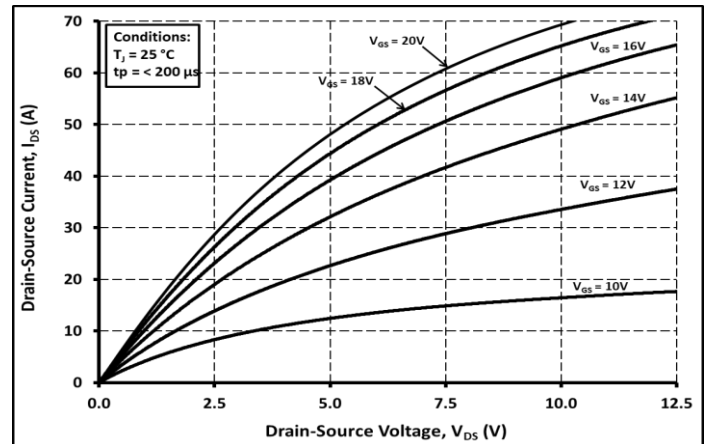


Figure 2.

Output Characteristics $T_{vj} = 25\text{ }^{\circ}\text{C}$

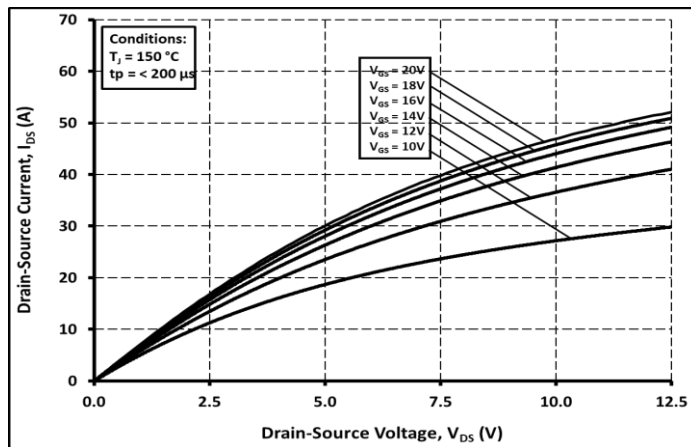


Figure 3.

Output Characteristics $T_{vj} = 150\text{ }^{\circ}\text{C}$

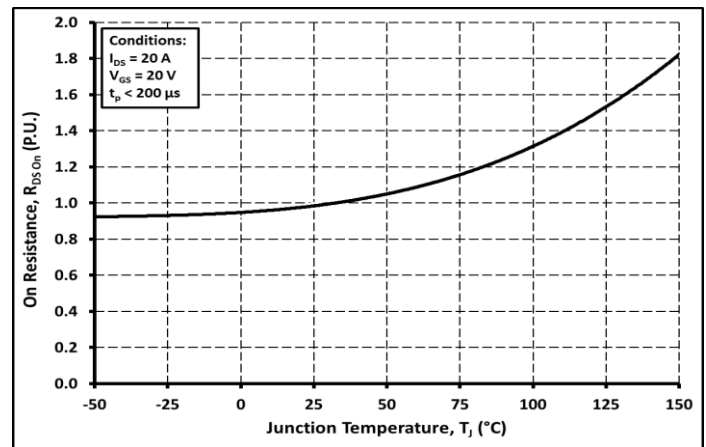


Figure 4.

Normalized On-Resistance vs. Temperature

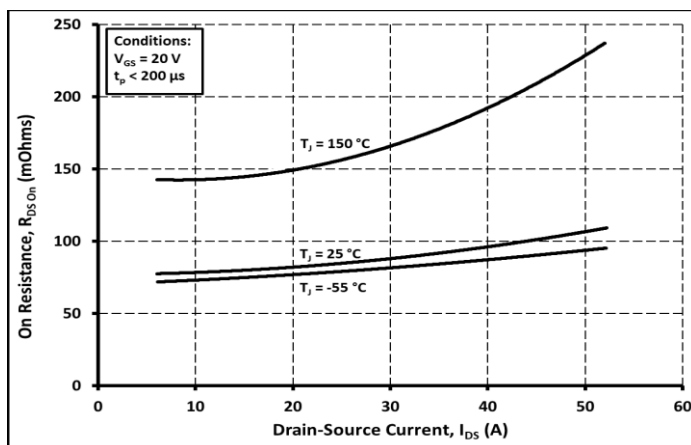


Figure 5.

On-Resistance vs. Drain Current For Various Temperatures

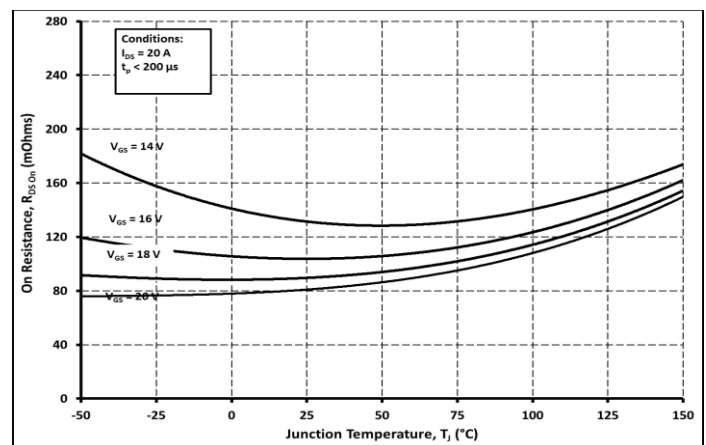


Figure 6.

On-Resistance vs. Temperature For Various Gate Voltages

Typical Performance

All the graphs are based on a die placed in a TO-247-4L package.

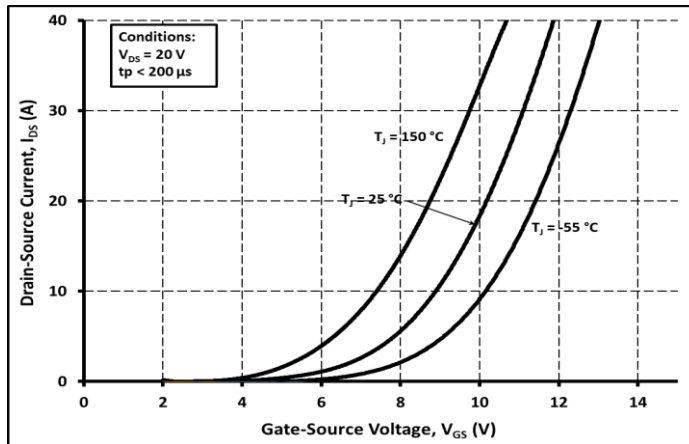


Figure 7.

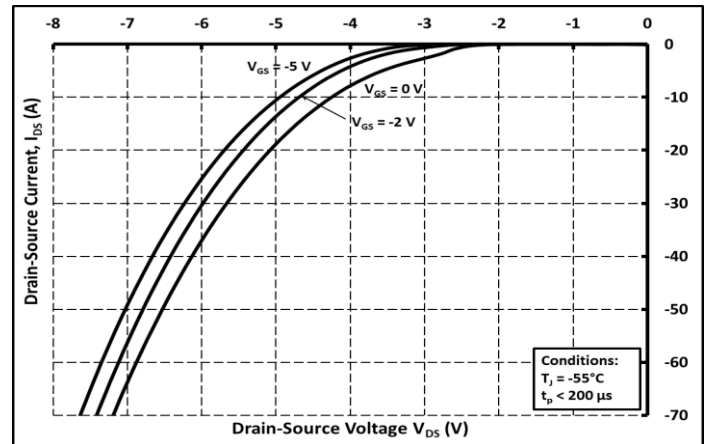


Figure 8.

Transfer Characteristic For Various Junction Temperatures

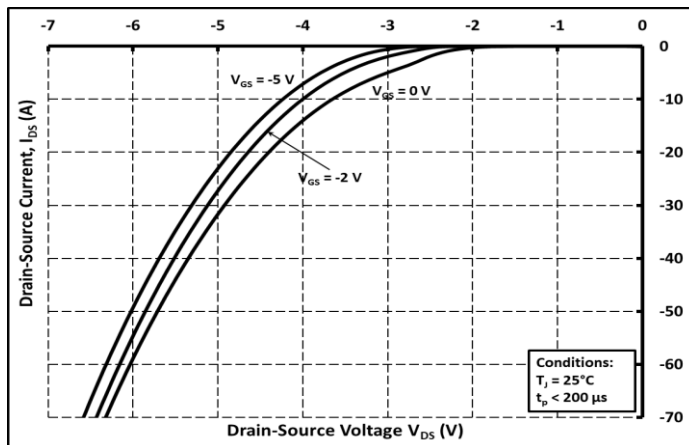


Figure 9.

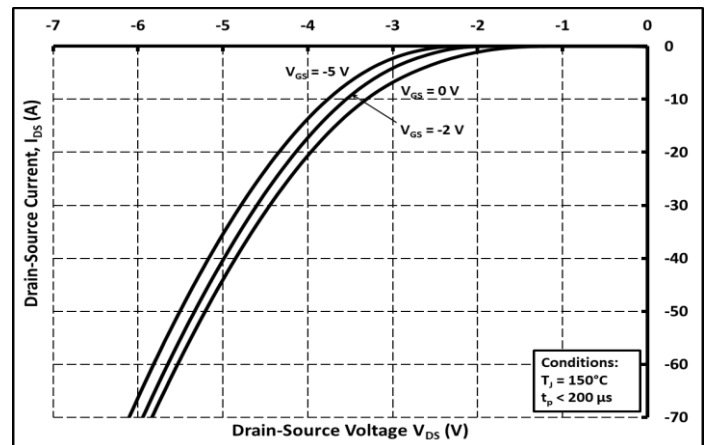


Figure 10.

Body Diode Characteristic at $T_{vj} = 25^\circ\text{C}$

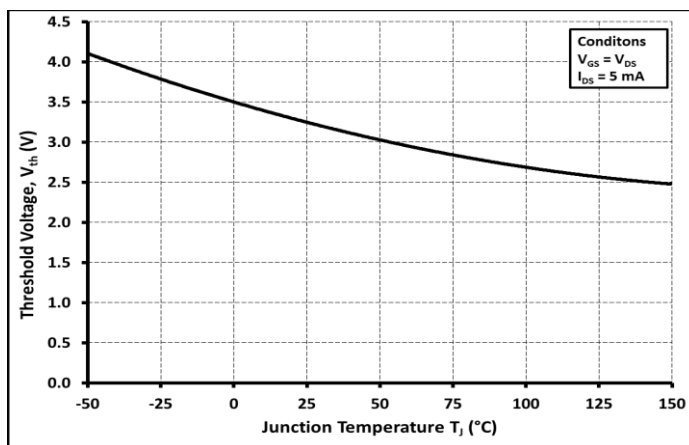


Figure 11.

Body Diode Characteristic at $T_{vj} = 150^\circ\text{C}$

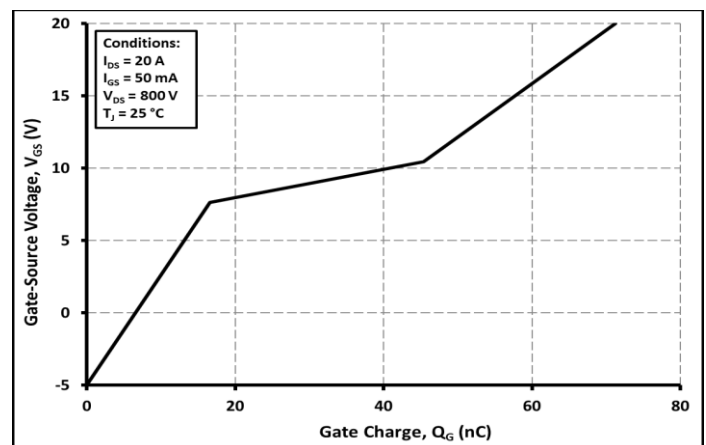


Figure 12.

Threshold Voltage vs. Temperature

Gate Charge Characteristics

Typical Performance

All the graphs are based on a die placed in a TO-247-4L package.

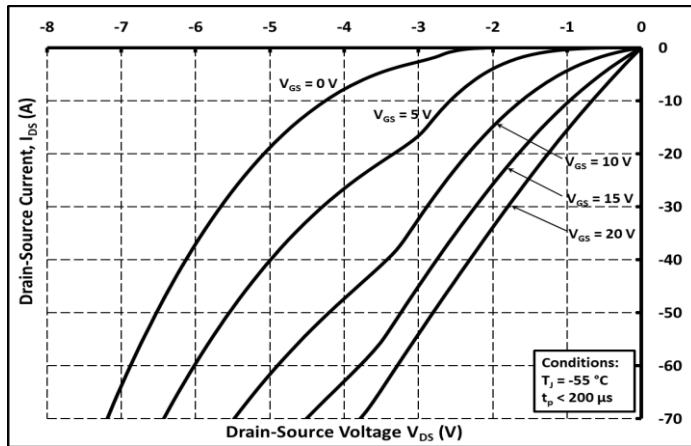


Figure 13.

3rd Quadrant Characteristic at $T_{vj} = -55\text{ }^{\circ}\text{C}$

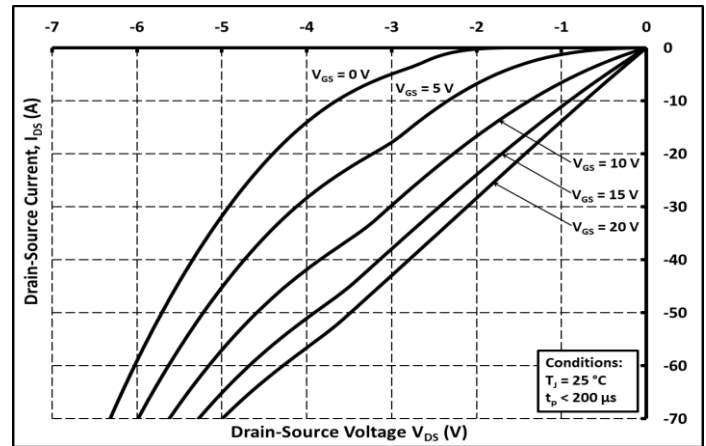


Figure 14.

3rd Quadrant Characteristic at $T_{vj} = 25\text{ }^{\circ}\text{C}$

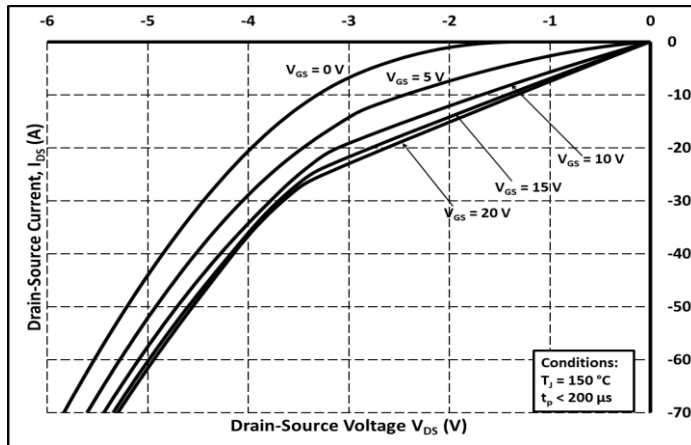


Figure 15.

3rd Quadrant Characteristic at $T_{vj} = 150\text{ }^{\circ}\text{C}$

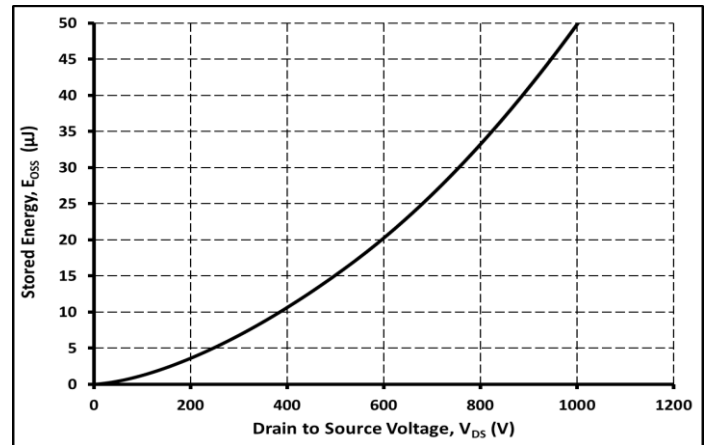


Figure 16.

Output Capacitor Stored Energy

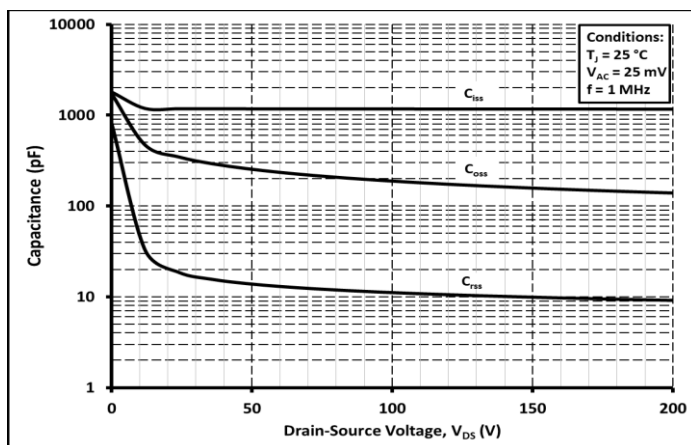


Figure 17.

Capacitances vs. Drain-Source Voltage (0-200V)

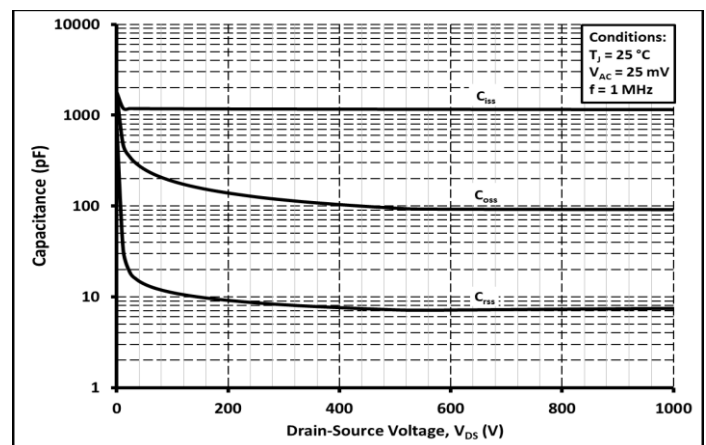
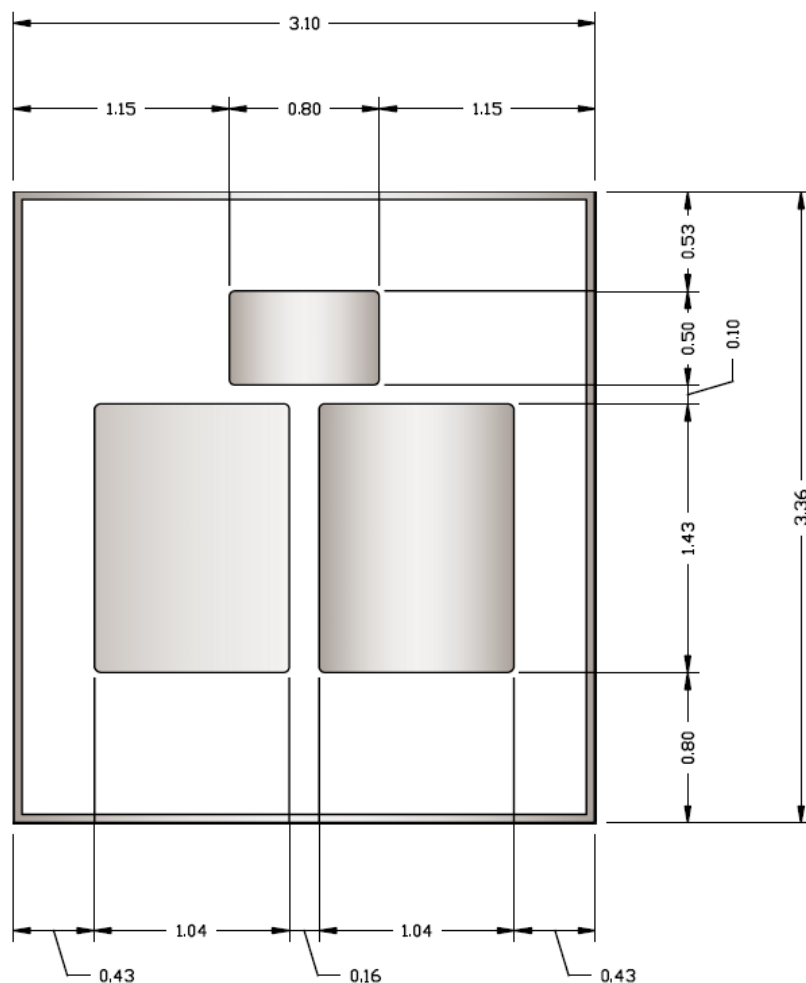


Figure 18.

Capacitances vs. Drain-Source Voltage (0-1200V)



Product Dimensions CPM2-1200-0080A



Product Dimensions CPM2-1200-0080A

Parameter	Typical	Units
Die Size (L x W)	3.10 x 3.36	mm
Exposed Source Pad Metal Dimensions	1.04 x 1.43	mm
Gate Pad Dimensions	0.80 x 0.50	mm
Chip Thickness ¹	180 ± 20	μm
Frontside (Source) metalization (Al)	4	μm
Frontside (Gate) metalization (Al)	4	μm
Backside (Drain) metalization (Ni:Au)	0.8 / 0.6	μm

¹ SiC wafer thickness



Product Ordering Information

Order Number	Description	Package
CPM2-1200-0080A-FY6	SiC MOSFET G2 IND 1200V/80mO UV MLT	Bare Die Product

Revision History

Revision History	Date of Change	Brief Summary
1	09/2020	Initial Release
2	12/22/2023	<ul style="list-style-type: none">• Template updated

Notes & Disclaimer

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Contact info:

4600 Silicon Drive
Durham, NC 27703 USA
Tel: +1.919.313.5300
www.wolfspeed.com/power